COMPONENTS MARKED ‘DNP’ SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE

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<th>BOARD #: PMP20637_winding</th>
<th>Rev B</th>
<th>SUN REV: Not In VersionControl</th>
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PLOT NAME = Top Assembly Drawing

GENERATED : 5/11/2017  5:10:47 PM   TEXAS INSTRUMENTS
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

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<th>PLOT NAME = Bottom Assembly Drawing</th>
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